L Number	Hits	Search Text	DB	Time stamp
1	2	("6555417").PN.	USPAT;	2004/01/09 14:43
			US-PGPUB;	2004/01/09 14:43
			EPO; JPO;	
			DERWENT:	1
			IBM TDB	1
-	1986	MEMS and cavity	USPAT:	2003/10/22 17:50
	1		US-PGPUB;	1
			EPO; JPO;	
	1		DERWENT;	
	128	(438/55),CCLS.	IBM_TDB	
	120	(436/33).CCLS.	USPAT;	2003/10/22 17:26
	J		US-PGPUB;	
	Í		EPO; JPO; DERWENT;	1
	1		IBM TDB	i
-	188	(438/33).CCLS,	USPAT;	2003/10/22 17:27
			US-PGPUB;	2003/10/22 17.27
			EPO; JPO;	í
			DERWENT;	
			IBM TDB	
-	272	(438/64).CCLS.	USPAT;	2003/10/22 17:27
	1		US-PGPUB;	1
	1		EPO; JPO;	
			DERWENT;	
_	168	(438/66).CCLS.	IBM_TDB	
	100	(430/00).CCLS.	USPAT;	2003/10/22 17:28
			US-PGPUB;	
			EPO; JPO; DERWENT;	1
			IBM TDB	1
-	2320	(438/106),CCLS.	USPAT;	2003/10/22 17:29
			US-PGPUB;	2003/10/22 1/.23
	l		EPO; JPO;	1
			DERWENT;	
			IBM TOB	
-	664	(438/126).CCLS.	USPAT;	2003/10/22 17:30
			US-PGPUB;	
			EPO; JPO;	
	!		DERWENT; IBM TDB	
- 1	1045	(438/118),CCLS.	USPAT;	2003/10/22 17:31
			US-PGPUB;	2003/10/22 17:31
			EPO; JPO;	
			DERWENT;	l i
			IBM TDB	
- 1	271	(438/110).CCLS.	USPAT;	2003/10/22 17:32
			US-PGPUB;	
			EPO; JPO;	
l			DERWENT;	
_	202	(438/51).CCLS.	IBM_TDB	
- 1	202	(100,01),0020.	USPAT;	2003/10/22 17:32
			US-PGPUB; EPO; JPO;	
ļ	- 1		DERWENT;	
i			IBM TDB	
-	593	(438/15).CCLS.	USPAT;	2003/10/22 17:32
1	I		US-PGPUB;	,10,20,22
1			EPO; JPO;	
	i		DERWENT;	
_	742	(216 (2) 227 2	IBM_TDB	İ
- 1	/42	(216/2).CCLS.	USPAT;	2003/10/22 17:47
- 1	1		US-PGPUB;	
1	- 1		EPO; JPO;	
	i		DERWENT;	
- 1	1737	MEMS and (cavity or cavities) and (cap or	IBM_TDB USPAT;	2002/10/22 12:22
		capped or capping or seal\$3 or cover\$3 or	USPAT; US-PGPUB;	2003/10/22 17:37
		encapsulat\$3)	EPO; JPO;	
			DERWENT;	

-	1436		USPAT;	2003/10/22 17:4
		capped or capping or seal\$3 or cover\$3 or	US-PGPUB;	2003/10/22 17,9
	1	encapsulat\$3) and (cut\$3 or etch\$3)	EPO; JPO;	
	1		DERWENT;	
	215	(MEMS and (packag\$3)).ab.	IBM_TDB USPAT;	1
		the	US-PGPUB;	2003/10/22 17:3
			EPO; JPO;	
		i	DERWENT;	
	63	Arman I I I I	IBM TDB	
	0.5			2003/10/22 17:4
	1	capped or capping or seal\$3 or cover\$3 or encapsulat\$3)).ab.	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	1
-	286	(216/11).CCLS.	USPAT;	2003/10/22 18:29
		l .	US-PGPUB;	
	1		EPO; JPO;	1
			DERWENT;	
	425	(216/17).CCLS.	IBM_TDB	
	1		USPAT;	2003/10/22 17:48
	í		US-PGPUB; EPO; JPO;	
	1		DERWENT;	
		l	IBM TDB	1
	909	(216/20).CCLS.	USPAT;	2003/10/22 17:49
			US-PGPUB;	
	1		EPO; JPO;	
			DERWENT;	
	644	(216/24), CCLS.	IBM_TDB USPAT;	10000/00/00
			US-PGPUB;	2003/10/22 17:50
	í l		EPO; JPO;	
	1 1		DERWENT;	
	2311	MTMO 1	IBM TDB	
	2011	MEMS and (cavity or recess)	USPAT;	2003/10/22 18:17
			US-PGPUB; EPO; JPO;	
	1 1		DERWENT;	
	!		IBM TDB	i
	480	(216/33).CCLS.	USPĀT;	2003/10/22 17:56
	1 1		US-PGPUB;	
	j		EPO; JPO;	1
	] [		DERWENT;	1
	123	(216/36).CCLS.	IBM TDB USPAT;	2003/10/22 17 54
			US-PGPUB;	2003/10/22 17:54
	1 1		EPO; JPO;	
	í I		DERWENT;	
	10	((216/33).CCLS.) and mems	IBM_TDB	
	101	(LLO, 55).CCLS.) and mems	USPAT;	2003/10/22 17:54
	! !		US-PGPUB;	
	1		EPO; JPO; DERWENT;	
			IBM TDB	
	80	(((438/25).CCLS.) or ((438/55).CCLS.) or	USPAT;	2003/10/22 18:00
- 1		((438/33).CCLS.) or ((438/64).CCLS.) or	US-PGPUB;	
		((438/66).CCLS.) or ((438/106).CCLS.) or	EPO; JPO;	
- 1		((438/127).CCLS.) or ((438/126).CCLS.) or ((438/118).CCLS.) or ((438/110).CCLS.) or	DERWENT;	
- 1		((438/51).CCLS.) or ((438/15).CCLS.) or	IBM_TDB	
- 1	1.1	MEMS		
- 1	141	(((216/2).CCLS.) or ((216/11).CCLS.) or	USPAT;	2004/01/09 12:46
		((216/17).CCLS.) or ((216/20).CCLS.) or	US-PGPUB,	2004/01/09 12:46
		((216/24).CCLS.) or ((216/33).CCLS.) or	EPO; JPO;	
- 1	- 1	((216/36).CCLS.)) and MEMS	DERWENT;	
			IBM TDB	

-	215		USPAT;	2003/10/22 18:00
		((438/33).CCLS.) or ((438/64).CCLS.) or	US-PGPUB;	1
		((438/66).CCLS.) or ((438/106).CCLS.) or	EPO; JPO;	
		((438/127).CCLS.) or ((438/126).CCLS.) or ((438/118).CCLS.) or ((438/110).CCLS.) or	DERWENT; IBM TDB	
		((438/51).CCLS.) or ((438/15).CCLS.)) and	IBM_IDB	
		MEMS) or ((((216/2).CCLS.) or	1	
		((216/11).CCLS.) or ((216/17).CCLS.) or		
		((216/20).CCLS.) or ((216/24).CCLS.) or		
		((216/33).CCLS.) or ((216/36).CCLS.)) and		
	20	MEMS)		
-	20	((wafer adj bonding) or (wafer adj cap\$4)).ti. and MEMS	USPAT;	2003/10/22 18:18
		Capta//.ci. and mens	US-PGPUB; EPO; JPO;	
	J		DERWENT;	
	i		IBM TDB	
-	1567	MEMS and (cavity or recess) and cap\$4	USPAT;	2003/10/22 18:37
			US-PGPUB;	
	Į.		EPO; JPO;	
			DERWENT;	1
_	49	MEMS and (cavity or recess) and (wafer ad)	IBM TOB	1
	1 49	cap\$4)	USPAT; US-PGPUB;	2003/10/22 18:20
	1		EPO; JPO;	
	1		DERWENT;	
	1		IBM TDB	1
-	99	MEMS and (cavity or recess) and (wafer	USPAT;	2003/10/22 18:27
		near3 cap\$4)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
-	27	(MEMS and package).ti.	IBM TDB USPAT;	2003/10/22 18:28
	1	(mino dia package) .cr.	US-PGPUB;	2003/10/22 18:28
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	803	(257/433).CCLS.	USPAT;	2003/10/22 18:31
	!		US-PGPUB;	i
			EPO; JPO; DERWENT;	
			IBM TDB	
-	816	(257/443).CCLS.	USPĀT;	2003/10/22 18:32
	i		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	1596	((257/433).CCLS.) or ((257/443).CCLS.)	IBM_TDB	
	1 2000	((23//443).CCLS.)	USPĀT; US-PGPUB;	2003/10/22 18:33
			EPO; JPO;	!
			DERWENT:	1
	_		IBM TDB	
-	561	(257/466).CCLS.	USPAT;	2003/10/22 18:34
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
-	334	MEMS and (cavity or recess) and cap\$4 and	IBM TDB USPAT;	2003/10/22 18:37
	-/*	dic\$3	US-PGPUB;	2003/10/22 18:3/
			EPO; JPO;	
	( )		DERWENT;	
	ا ا		IBM_TDB	
-	2	("5323051").PN.	USPAT;	2003/10/22 19:07
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
-	154	(438/25).CCLS.	USPAT:	2004/01/08 15:17
			US-PGPUB;	1/01/00 13:1/
			EPO; JPO;	
	1 1		DERWENT;	
			IBM TDB	

-	647	MEMS and (cavity or cavities) and (cap or capped or capping)	USPAT; US-PGPUB;	2004/01/08 15:17
-	111	MEMS with (cap or capped or capping)	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/01/08 15:40
-	56	MEMS and (cap or capped or capping) same (diced or dicing or dice)	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/01/08 15:53
-	15	(MEMS and (cap or capped or capping) and (diced or dicing or dice)).ab.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/01/09 10:25
-	11	("4742432"   "4889587"   "5230759"   "5656776"   "5798557"   "5824177"   "5915168"   "5923995"   "6136212"   "6255741"   "6379988"), PN.	IBM_TDB USPAT	2004/01/08 15:47
-	886	(438/108).CCLs.	USPAT; US-PGPUB; EPO; JPO;	2004/01/08 15:54
-	674	(438/113).CCLS.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/01/08 15:54
-	920	(438/127).CCLS.	DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO;	2004/01/08 15:55
-	62	(MEMS and (cap or capped or capping)).ab.	DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO;	2004/01/09 12:48
-	18	(wafer adj cap\$4).ab. and MEMS	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/01/09 12:46
-	23	(((216/2).CCLS.) or ((216/11).CCLS.) or ((216/17).CCLS.) or ((216/20).CCLS.) or ((216/24).CCLS.) or ((216/33).CCLS.) or ((216/36).CCLS.)) and MEMS and (cap or	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/01/09 12:47
-	21	(MEMS) or microstructure\$1 or micromechanical or microelectromechanical) and (cap or capped or capping)).ti.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT:	2004/01/09 12:49
	L		IBM_TDB	